

AMENDMENTS TO THE CLAIMS:

Kindly amend claim 7, as shown below.

This listing of claims will replace all prior versions and listings of claims in the
Application:

Claim 1 (original): A semiconductor device comprising:

a semiconductor chip mounted on a mounting substrate;

a first resin filling a gap between the semiconductor chip and the mounting substrate;

a stiffener surrounding the semiconductor chip; and

a second resin filling a space between the semiconductor chip and the stiffener in
contact with the first resin, the first resin being different in a thermal expansion coefficient
from the second resin.

Claim 2 (original): The semiconductor device as claimed in claim 1, wherein a
thermal expansion coefficient of the second resin is smaller than a thermal expansion
coefficient of the first resin.

Claim 3 (original): The semiconductor device as claimed in claim 2, wherein the
stiffener is adhered to the mounting substrate with a resin the same as the second resin.

Claim 4 (original): The semiconductor device as claimed in claim 1, wherein the first
resin includes an underfill part filling the gap between the semiconductor chip and the
mounting substrate, and a fillet part extended from a region of the semiconductor chip.

Claim 5 (original): The semiconductor device as claimed in claim 1, wherein the
stiffener is adhered to the mounting substrate with a first adhesive being larger in a thermal
expansion coefficient than the second resin.

Claim 6 (original): The semiconductor device as claimed in claim 4, wherein the

second resin is in contact with inner walls of the stiffener, the fillet part, the mounting substrate and each of side faces of the semiconductor chip.

Claim 7 (currently amended): A semiconductor device comprising:

a semiconductor chip mounted on a mounting substrate;

a first resin filling a gap between the semiconductor chip and the mounting substrate;

a stiffener surrounding the semiconductor chip;

a second resin filling a space between the semiconductor chip and the stiffener in contact with the first resin, the first resin being different in a thermal expansion coefficient from the second resin; and

a lid for covering the stiffener and the semiconductor chip, wherein the lid is bonded to the stiffener and a backside of the semiconductor chip with ~~a second~~ an adhesive.

Claim 8 (original): The semiconductor device as claimed in claim 7, wherein the second resin is in contact with an inner wall of the lid.

Claim 9 (original): The semiconductor device as claimed in claim 1, wherein an elastic modulus of the second resin is larger than an elastic modulus of the first resin.

Claim 10 (withdrawn): The semiconductor device as claimed in claim 2, wherein the stiffener has a plurality of concave portions facing the mounting substrate.

Claim 11 (withdrawn): The semiconductor device as claimed in claim 10, wherein a planer shape of the stiffener is rectangular, and the concave portion is formed on each corner of the stiffener.

Claim 12 (withdrawn): The semiconductor device as claimed in claim 10, wherein each of concave portions is filled with a resin the same as the second resin.

Claim 13 (withdrawn): The semiconductor device as claimed in claim 2, wherein the

stiffener end surface facing the mounting substrate is convexo-concave, and a gap between the mounting substrate and concave portion of the stiffener end surface is filled with a first adhesive.

Claim 14 (withdrawn): The semiconductor device as claimed in claim 2, wherein the stiffener end surface facing the mounting substrate is convexo-concave, and a gap between the mounting substrate and concave portion of the stiffener end surface is filled with a resin the same as the second resin.

Claim 15 (withdrawn): The semiconductor device as claimed in claim 2, wherein the stiffener end surface facing the mounting substrate is convexo-concave, the mounting substrate includes a first metal layer in a region facing the stiffener, the stiffener includes a second metal layer on a surface of a convex portion, and the mounting substrate and the convex portion of the stiffener are connected to each other by a low-melting alloy.

Claim 16 (original): The semiconductor device as claimed in claim 1, wherein the stiffener is made of a material selected from the group consisting of Cu, SUS, Al, alumina, silicon, aluminum nitride, and resin.

Claim 17 (original): The semiconductor device as claimed in claim 1, wherein each of the first resin and the second resin essentially contains a resin selected from a group consisting of epoxy, polyolefin, silicon, cyanate ester, polyimide, polynorbornene resins.

Claim 18 (withdrawn): The semiconductor device as claimed in claim 1, wherein a gap member different from the first adhesive is partially arranged between the mounting substrate and the stiffener.

Claim 19 (withdrawn): The semiconductor device as claimed in claim 18, wherein the gap member is made of a low-melting alloy.